Rochester Electronics

Datasheet

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
    - Class Q Military
    - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

    - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

FAIRCHILD SEMICONDUCTOR®

May 2007

74F240, 74F244
Octal Buffers/Line Drivers with 3-STATE Outputs

Features

- 3-STATE outputs drive bus lines or buffer memory address registers
- Outputs sink 64mA (48mA mil)
- 12mA source current
- Input clamp diodes limit high-speed termination effects

General Description

The 74F240 and 74F244 are octal buffers and line drivers designed to be employed as memory and address drivers, clock drivers and bus-oriented transmitters/receivers which provide improved PC and board density.

Ordering Information

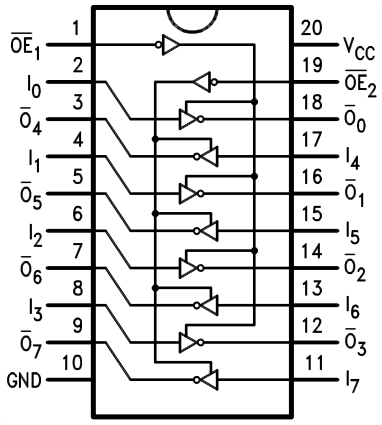
Order Code	Package Number	Package Description
74F240SC(1)	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74F240SJ(1)	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F240PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
74F244SC(1)	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74F244SJ(1)	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F244MSA(1)	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74F244PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Note:

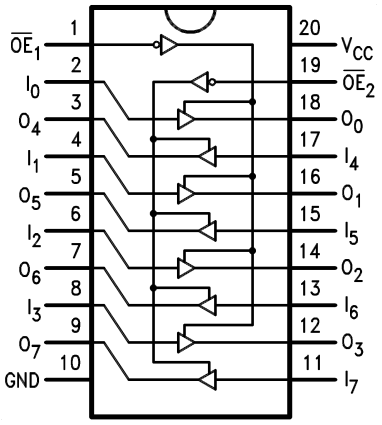
1. Devices also available in Tape and Reel. Specify by appending the suffix letter “X” to the ordering number.

Connection Diagrams

74F240

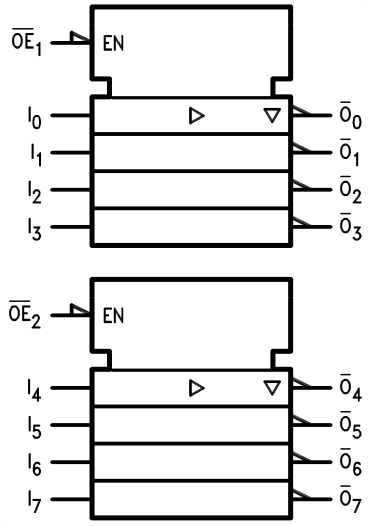


74F244

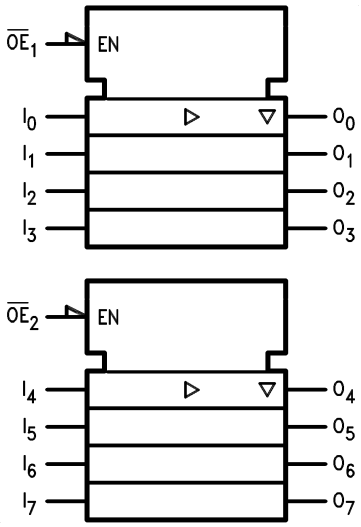


Logic Symbols

IEEE/IEC
74F240



IEEE/IEC
74F244



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH} / I_{IL}, Output I_{OH} / I_{OL}
$\overline{OE}_1$, $\overline{OE}_2$	3-STATE Output Enable Input (Active LOW)	1.0 / 1.667	20µA / –1mA
OE_2	3-STATE Output Enable Input (Active HIGH)	1.0 / 1.667	20µA / –1mA
I_0–I_7	Inputs (74F240)	1.0 / 1.667(2)	20µA / –1mA
I_0–I_7	Inputs (74F244)	1.0 / 2.667(2)	20µA / –1.6mA
$\overline{O}_0$–$\overline{O}_7$, O_0–O_7	Outputs	600 / 106.6 (80)	–12mA / 64mA (48mA)

Note:

2. Worst-case 74F240 enabled; 74F244 disabled.

Truth Tables

74F240

$\overline{OE}_1$	D_{1n}	O_{1n}	$\overline{OE}_2$	D_{2n}	O_{2n}
H	X	Z	H	X	Z
L	H	L	L	H	L
L	L	H	L	L	H

74F244

$\overline{OE}_1$	D_{1n}	O_{1n}	$\overline{OE}_2$	D_{2n}	O_{2n}
H	X	Z	H	X	Z
L	H	H	L	H	H
L	L	L	L	L	L

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
T_{STG}	Storage Temperature	–65°C to +150°C
T_A	Ambient Temperature Under Bias	–55°C to +125°C
T_J	Junction Temperature Under Bias	–55°C to +150°C
V_{CC}	V_{CC} Pin Potential to Ground Pin	–0.5V to +7.0V
V_{IN}	Input Voltage(3)	–0.5V to +7.0V
I_{IN}	Input Current(3)	–30mA to +5.0mA
V_O	Voltage Applied to Output in HIGH State (with V_{CC} = 0V) Standard Output 3-STATE Output	 –0.5V to V_{CC} –0.5V to 5.5V
	Current Applied to Output in LOW State (Max.)	twice the rated I_{OL} (mA)
	ESD Last Passing Voltage (Min.)	4000V

Note:

3. Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
T_A	Free Air Ambient Temperature	0°C to +70°C
V_{CC}	Supply Voltage	+4.5V to +5.5V

DC Electrical Characteristics

Symbol	Parameter		V_{CC}	Conditions	Min.	Typ.	Max.	Units
V_{IH}	Input HIGH Voltage			Recognized as a HIGH Signal	2.0			V
V_{IL}	Input LOW Voltage			Recognized as a LOW Signal			0.8	V
V_{CD}	Input Clamp Diode Voltage		Min.	I_{IN} = –18mA			–1.2	V
V_{OH}	Output HIGH Voltage	10% V_{CC}	Min.	I_{OH} = –3mA	2.4			V
		10% V_{CC}		I_{OH} = –15mA	2.0			
		5% V_{CC}		I_{OH} = –3mA	2.7			
V_{OL}	Output LOW Voltage	10% V_{CC}	Min.	I_{OL} = 64mA			0.55	V
I_{IH}	Input HIGH Current		Max.	V_{IN} = 2.7V			5.0	µA
I_{BVI}	Input HIGH Current Breakdown Test		Max.	V_{IN} = 7.0V			7.0	µA
I_{CEX}	Output HIGH Leakage Current		Max.	V_{OUT} = V_{CC}			50	µA
V_{ID}	Input Leakage Test		0.0	I_{ID} = 1.9µA	4.75			V
				All Other Pins Grounded				
I_{OD}	Output Leakage Circuit Current		0.0	V_{IOD} = 150mV			3.75	µA
				All Other Pins Grounded				
I_{IL}	Input LOW Current		Max.	V_{IN} = 0.5V ($\overline{OE}_1$, $\overline{OE}_2$, OE_2, D_n (74F240))			–1.0	mA
				V_{IN} = 0.5V (D_n (74F244))			–1.6	
I_{OZH}	Output Leakage Current		Max.	V_{OUT} = 2.7V			50	µA
I_{OZL}	Output Leakage Current		Max.	V_{OUT} = 0.5V			–50	µA
I_{OS}	Output Short-Circuit Current		Max.	V_{OUT} = 0V	–100		–225	mA
I_{ZZ}	Bus Drainage Test		0.0V	V_{OUT} = 5.25V			500	µA
I_{CCH}	Power Supply Current (74F240)		Max.	V_O = HIGH		19	29	mA
I_{CCL}	Power Supply Current (74F240)		Max.	V_O = LOW		50	75	mA
I_{CCZ}	Power Supply Current (74F240)		Max.	V_O = HIGH Z		42	63	mA
I_{CCH}	Power Supply Current (74F244)		Max.	V_O = HIGH		40	60	mA
I_{CCL}	Power Supply Current (74F244)		Max.	V_O = LOW		60	90	mA
I_{CCZ}	Power Supply Current (74F244)		Max.	V_O = HIGH Z		60	90	mA

AC Electrical Characteristics

Symbol	Parameter	T_A = +25°C, V_{CC} = +5.0V, C_L = 50pF			T_A = –55°C to +125°C, V_{CC} = 5.0V, C_L = 50pF		T_A = 0°C to +70°C, V_{CC} = 5.0V, C_L = 50pF		Units
		Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
t_{PLH}, t_{PHL}	Propagation Delay Data to Output (74F240)	3.0	5.1	7.0	3.0	9.0	3.0	8.0	ns
		2.0	3.5	4.7	2.0	6.0	2.0	5.7	
t_{PZH}, t_{PZL}	Output Enable Time (74F240)	2.0	3.5	4.7	2.0	6.5	2.0	5.7	ns
		4.0	6.9	9.0	4.0	10.5	4.0	10.0	
t_{PHZ}, t_{PLZ}	Output Disable Time (74F240)	2.0	4.0	5.3	2.0	6.5	2.0	6.3	
		2.0	6.0	8.0	2.0	12.5	2.0	9.5	
t_{PLH}, t_{PHL}	Propagation Delay, Data to Output (74F244)	2.5	4.0	5.2	2.0	6.5	2.5	6.2	ns
		2.5	4.0	5.2	2.0	7.0	2.5	6.5	
t_{PZH}, t_{PZL}	Output Enable Time (74F244)	2.0	4.3	5.7	2.0	7.0	2.0	6.7	ns
		2.0	5.4	7.0	2.0	8.5	2.0	8.0	
t_{PHZ}, t_{PLZ}	Output Disable Time (74F244)	2.0	4.5	6.0	2.0	7.0	2.0	7.0	
		2.0	4.5	6.0	2.0	7.5	2.0	7.0	

Physical Dimensions

Dimensions are in inches (millimeters) unless otherwise noted.

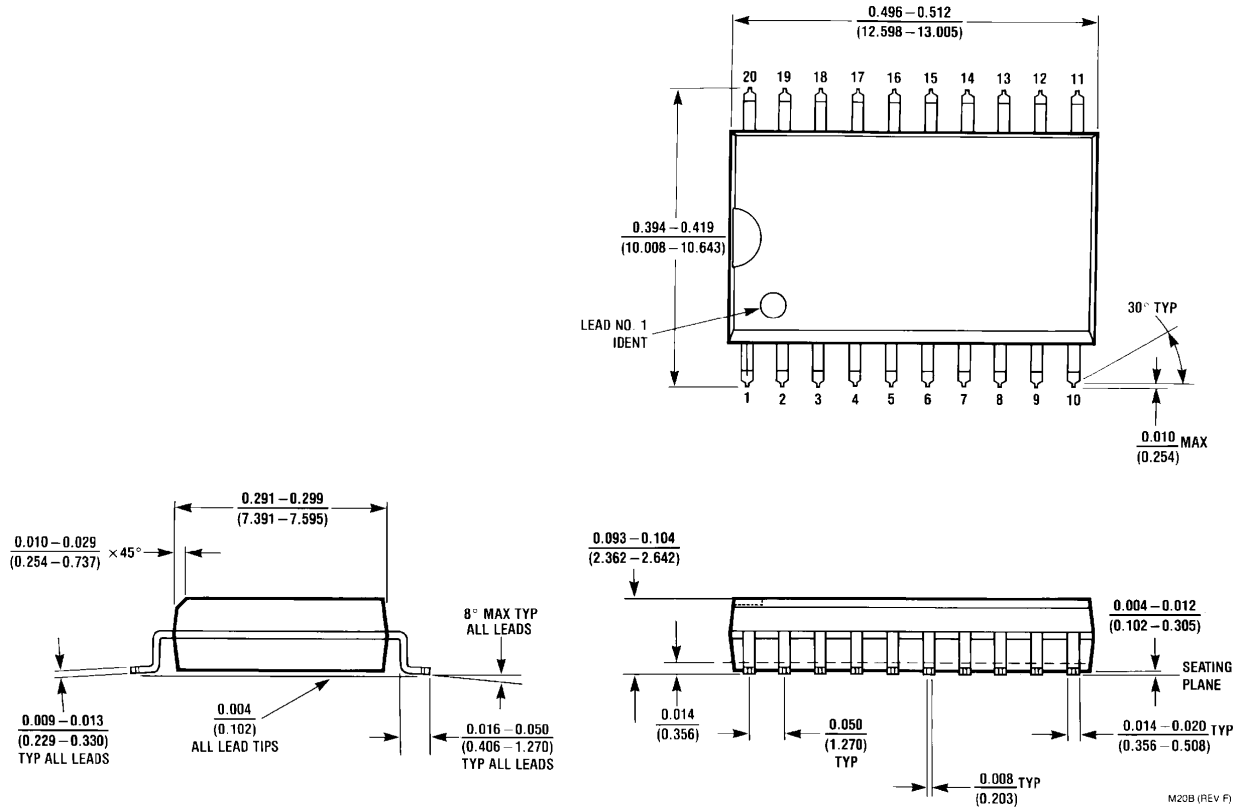
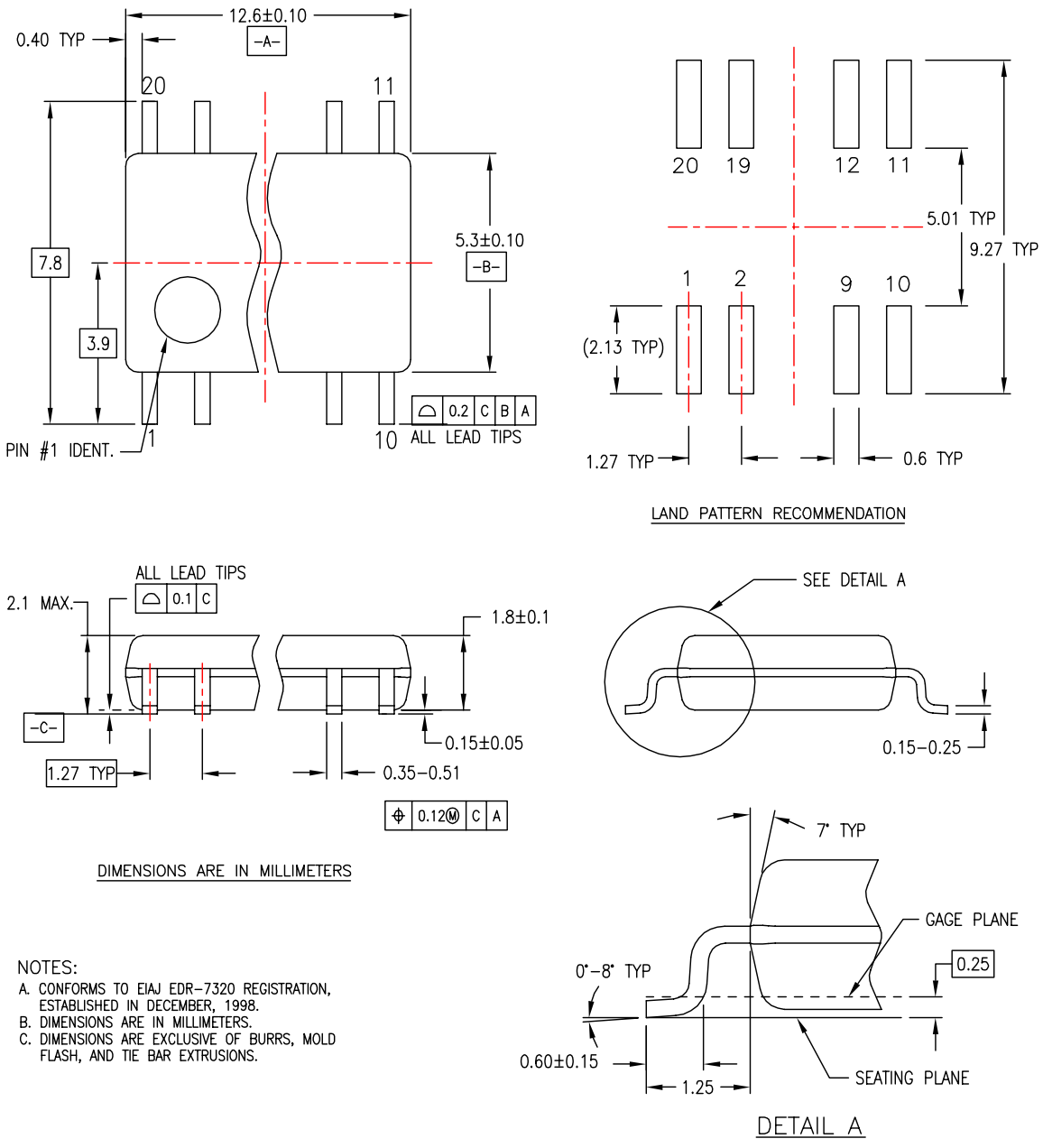


Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

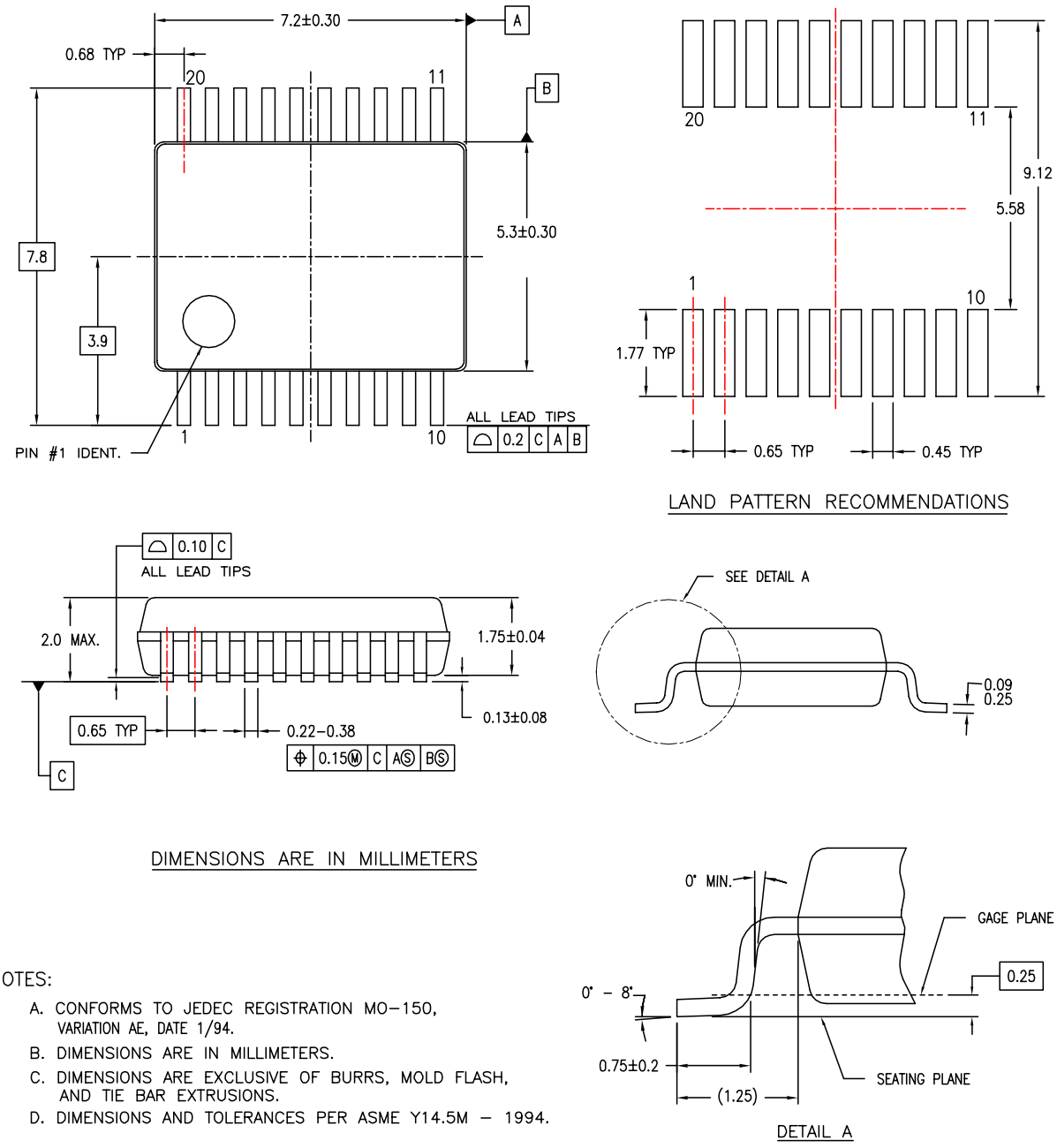
A. CONFORMS TO EIAJ EDR–7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DREVC

Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO–150, VARIATION AE, DATE 1/94.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M – 1994.

MSA20REVB

Figure 3. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
Package Number MSA20

Physical Dimensions (Continued)

Dimensions are in inches (millimeters) unless otherwise noted.

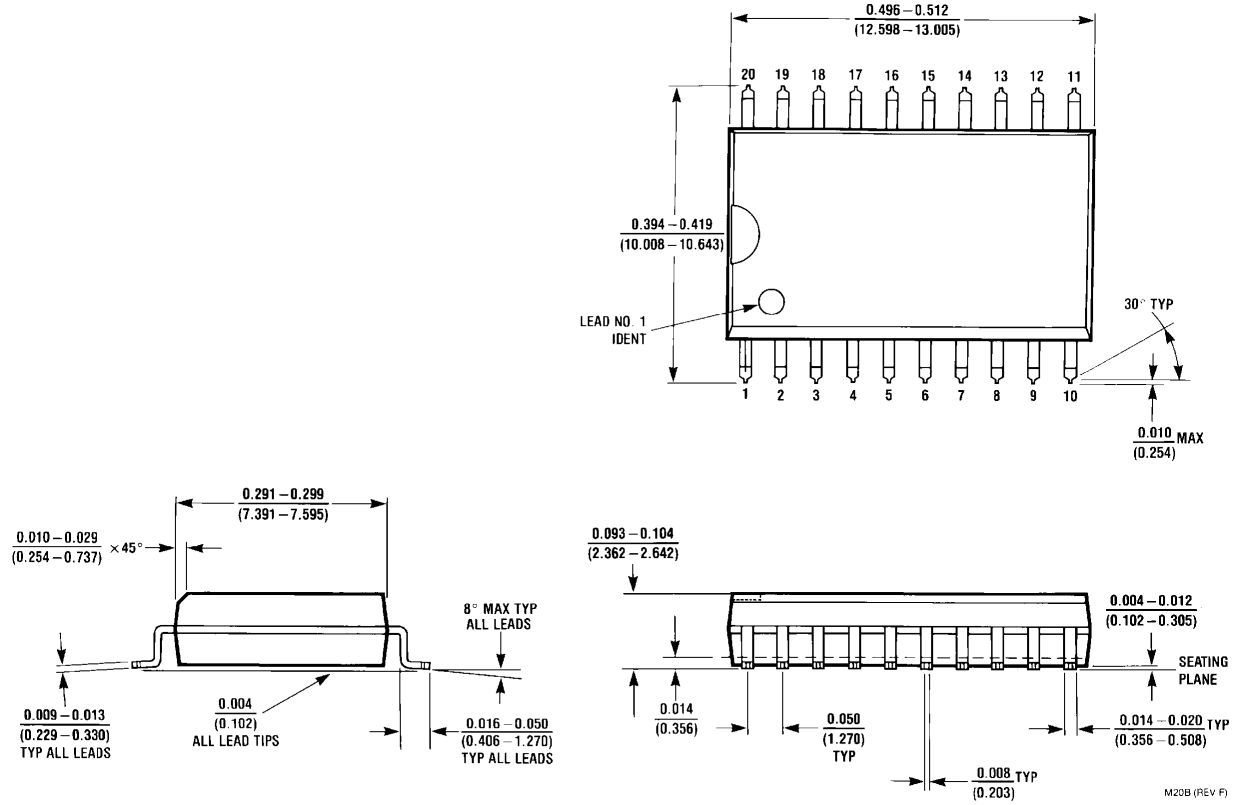


Figure 4. 20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N20A

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Rev. I26